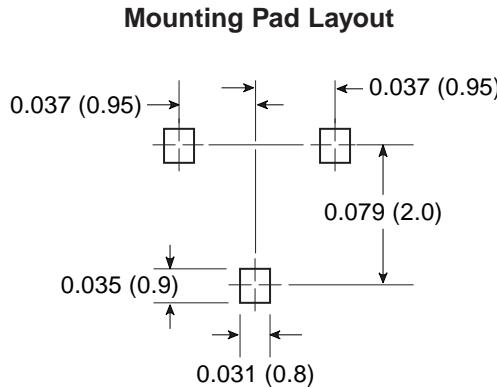
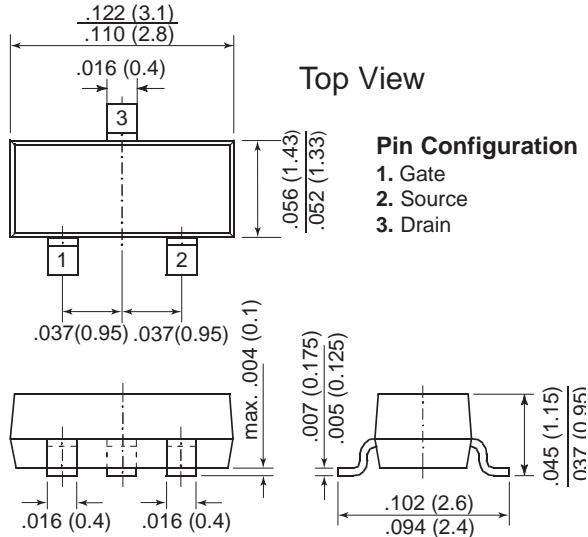


DMOS Transistors (P-Channel)



TO-263AB (SOT-23)



Dimensions in inches and (millimeters)

Features

- High input impedance
- High-speed switching
- No minority carrier storage time
- CMOS logic compatible input
- No thermal runaway
- No secondary breakdown

Mechanical Data

Case: SOT-23 Plastic Package

Weight: approx. 0.008 grams

Packaging Codes/Options:

E8/10K per 13" reel (8mm tape), 30K/box
E9/3K per 7" reel (8mm tape), 30K/box

Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	-V _{DSS}	60	V
Drain-Gate Voltage	-V _{DGS}	60	V
Gate-Source-Voltage (pulsed)	V _{GS}	±20	V
Drain Current (continuous)	-I _D	250	mA
Power Dissipation at T _{SB} = 50°C	P _{tot}	0.310 ⁽¹⁾	W
Thermal Resistance Junction to Substrate Backside	R _{θSB}	320 ⁽¹⁾	°C/W
Thermal Resistance Junction to Ambiant Air	R _{θJA}	450 ⁽¹⁾	°C/W
Junction Temperature	T _j	150	°C
Storage Temperature Range	T _s	-65 to +150	°C

Note:

(1) Device on Fiberglass Substrate, see layout on second page

DMOS Transistors (P-Channel)
Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$-V_{(\text{BR})\text{DSS}}$	$-I_D = 100\mu\text{A}, V_{GS} = 0$	60	90	—	V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{GS} = V_{DS}, -I_D = 1\text{mA}$	1.0	2.0	3.0	V
Gate-Body Leakage Current	$-I_{GSS}$	$-V_{GS} = 15\text{V}, V_{DS} = 0$	—	—	10	nA
Drain Cutoff Current	$-I_{DSS}$	$-V_{DS} = 25\text{V}, V_{GS} = 0$	—	—	0.5	μA
Drain-Source On-State Resistance	$R_{DS(\text{on})}$	$-V_{GS} = 10\text{V}, -I_D = 200\text{mA}$	—	3.5	5.0	Ω
Forward Transconductance	g_m	$-V_{DS} = 10\text{V}, -I_D = 200\text{mA}, f = 1\text{MHz}$	—	200	—	mS
Input Capacitance	C_{iss}	$-V_{DS} = 10\text{V}, V_{GS} = 0, f = 1\text{MHz}$	—	60	—	pF
Turn-On Time	t_{on}	$-V_{GS} = 10\text{V}, -V_{DS} = 10\text{V}$	—	5	—	ns
Turn-Off Time	t_{off}	$R_D = 100\Omega$	—	25	—	ns

Note:

(1)Device on fiberglass substrate, see layout

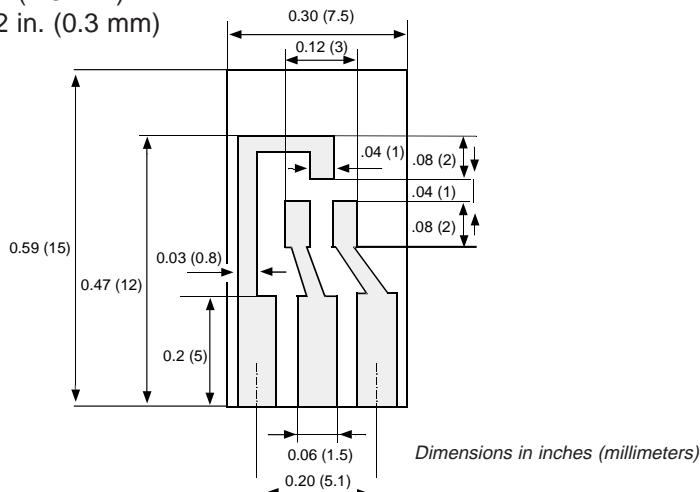
Inverse Diode

Parameters	Symbol	Test Condition	Value	Unit
Max. Forward Current (continuous)	I_F	$T_{\text{amb}} = 25^\circ\text{C}$	0.3	A
Forward Voltage Drop (typ.)	V_F	$V_{GS} = 0, I_F = 0.12\text{A}$ $T_j = 25^\circ\text{C}$	0.85	V

Layout for R_{thJA} test

Thickness: Fiberglass 0.059 in. (1.5 mm)

Copper leads 0.012 in. (0.3 mm)



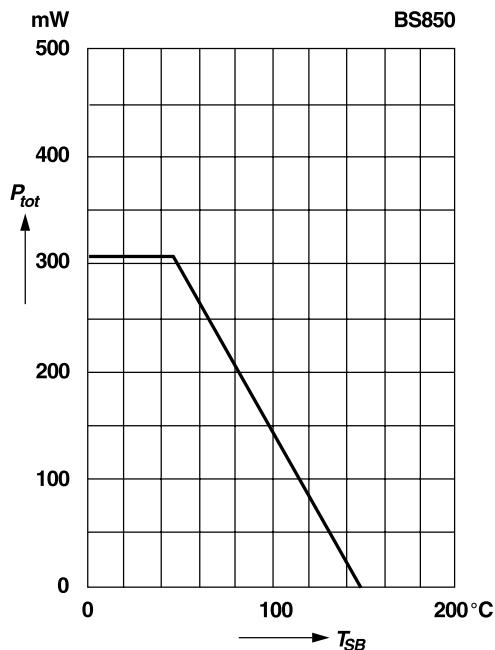
DMOS Transistors (P-Channel)

Ratings and Characteristic Curves

($T_A = 25^\circ\text{C}$ unless otherwise noted)

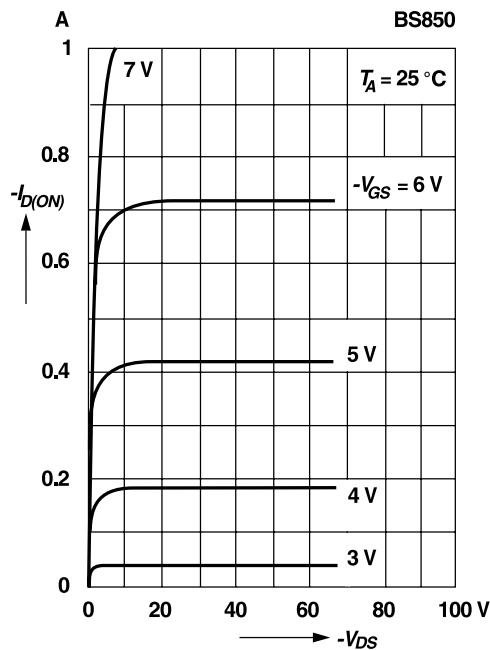
**Admissible power dissipation
versus temperature of substrate backside**

Device on fiberglass substrate, see layout



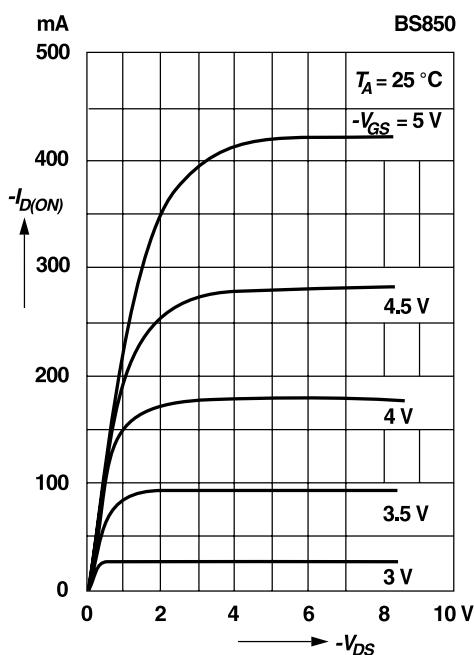
Output characteristics

Pulse test width 80 ms; pulse duty factor 1%

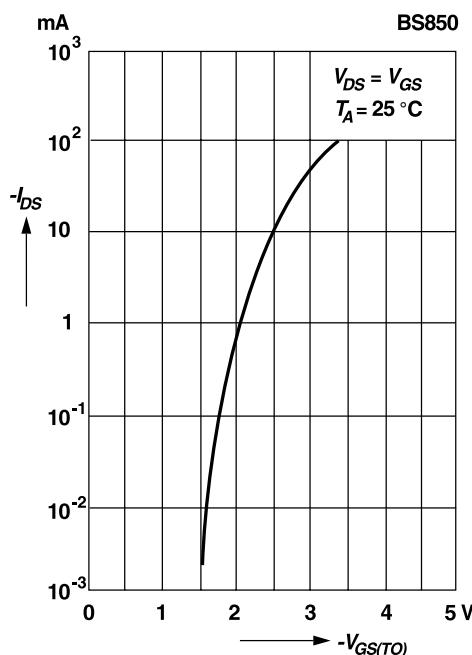


Saturation characteristics

Pulse test width 80 ms; pulse duty factor 1%



**Drain-source current
versus gate threshold voltage**

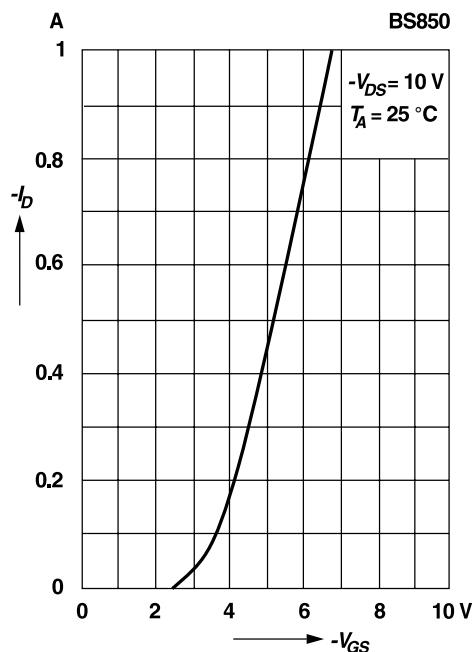


DMOS Transistors (P-Channel)

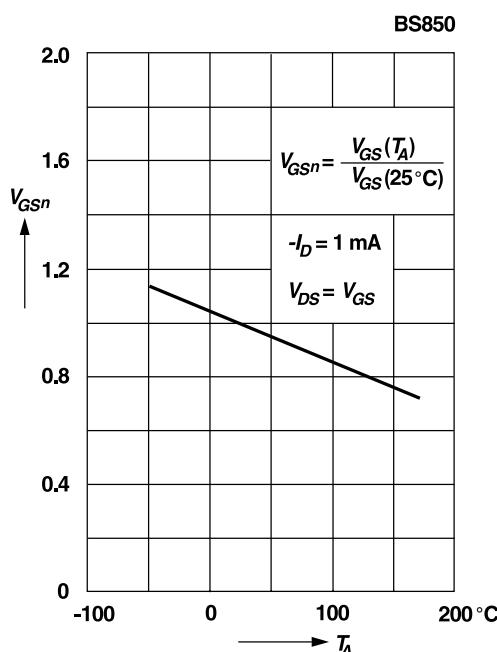
Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

**Drain current
versus gate-source voltage**

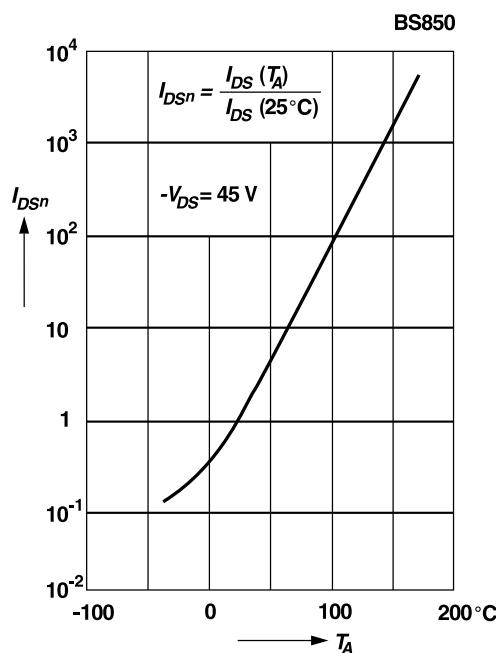
Pulse test width 80 ms; pulse duty factor 1%



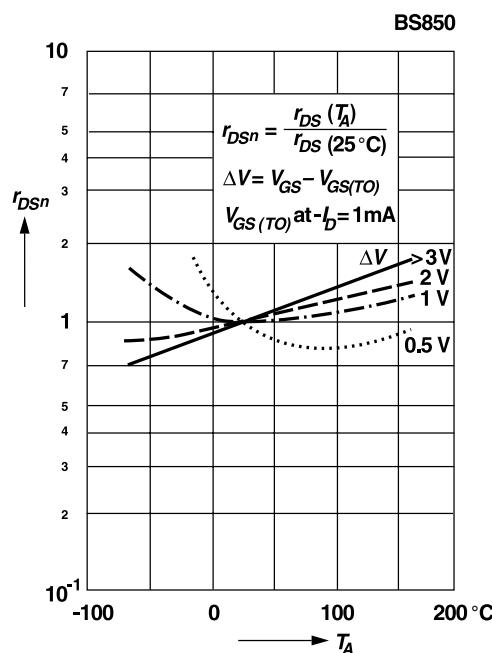
**Normalized gate-source voltage
versus temperature**



**Normalized drain-source current
versus temperature**



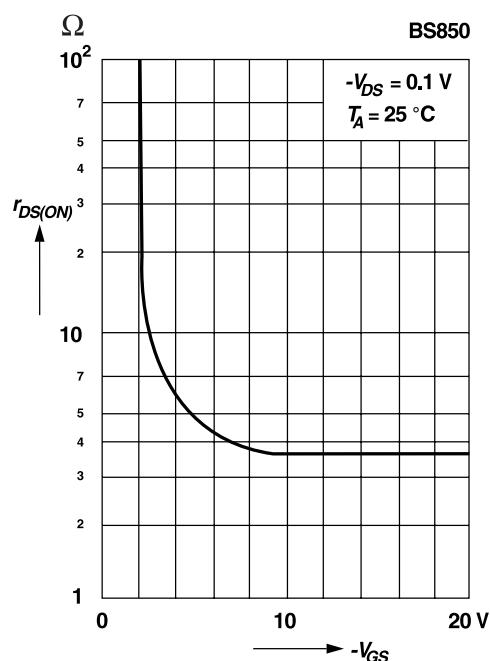
**Normalized drain-source resistance
versus temperature**



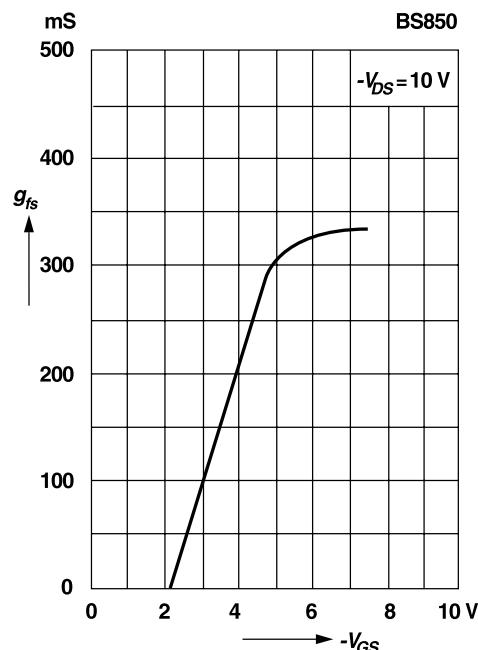
DMOS Transistors (P-Channel)

Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

**Drain-source resistance
versus gate-source voltage**

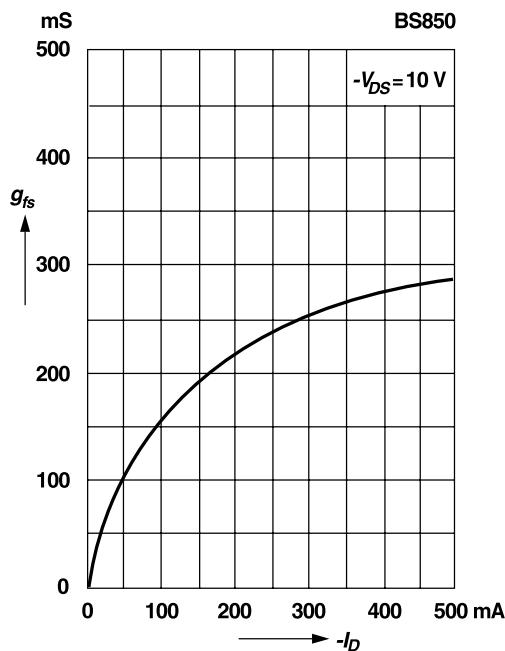


**Transconductance
versus gate-source voltage**
Pulse test width 80 ms; pulse duty factor 1%



**Transconductance
versus drain current**

Pulse test width 80 ms; pulse duty factor 1%



**Capacitance
versus drain-source voltage**

